ABSTRACT

RELIABLE METAL BUMPS ON TOP OF I/O PADS WITH TEST PROBE MARKS

A new method is provided for the creation of metal bumps over surfaces of I/O pads. The area in the surface of I/O pads, which have been used for I/O pads during wafer level semiconductor device testing, is removed in the immediate vicinity of the surface area where the test probe contacts the I/O pad. This removal uses methods of metal dry etching or wet etching.

(FIGURE 8a IS SUGGESTED FOR PUBLICATION)